

# **BUK6210-55C**

# N-channel TrenchMOS intermediate level FET Rev. 2 — 4 October 2010

**Product data sheet** 

#### 1. **Product profile**

## 1.1 General description

Intermediate level gate drive N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using advanced TrenchMOS technology. This product has been designed and qualified to the appropriate AEC Q101 standard for use in high performance automotive applications.

#### 1.2 Features and benefits

- AEC Q101 compliant
- Suitable for standard and logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

## 1.3 Applications

- 12 V and 24 V Automotive systems
- Electric and electro-hydraulic power steering
- Motors, lamps and solenoid control
- Start-Stop micro-hybrid applications
- Transmission control
- Ultra high performance power switching

#### 1.4 Quick reference data

Table 1. **Quick reference data** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \ge 25 \text{ °C}; T_j \le 175 \text{ °C}$	-	-	55	V
I <sub>D</sub>	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ °C};$ see <u>Figure 1</u>	-	-	78	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>	-	-	128	W
Static chara	acteristics					
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A};$ $T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 11}{}$	-	8.1	9.6	mΩ



Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Avalanche	ruggedness					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$\begin{split} I_D &= 78 \text{ A; } V_{sup} \leq 55 \text{ V;} \\ R_{GS} &= 50 \text{ \Omega; } V_{GS} = 10 \text{ V;} \\ T_{j(init)} &= 25 \text{ °C; } unclamped \end{split}$	-	-	94	mJ
Dynamic ch	naracteristics					
$Q_{GD}$	gate-drain charge	$I_D$ = 25 A; $V_{DS}$ = 44 V; $V_{GS}$ = 10 V; see <u>Figure 13</u> ; see <u>Figure 14</u>	-	19.5	-	nC

# 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	drain	mb	D
3	S	source		
mb	D	mounting base; connected to drain	1 3	mbb076 S
			SOT428 (DPAK)	

# 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK6210-55C	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

# 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C		-	55	V
$V_{GS}$	gate-source voltage	DC	<u>[1]</u>	-16	16	V
		Pulsed	[2]	-20	20	V
I <sub>D</sub>	drain current	$T_{mb}$ = 25 °C; $V_{GS}$ = 10 V; see <u>Figure 1</u>		-	78	Α
		$T_{mb} = 100  ^{\circ}\text{C};  V_{GS} = 10  \text{V};  \text{see}  \frac{\text{Figure 1}}{}$		-	55	Α
I <sub>DM</sub>	peak drain current	$T_{mb}$ = 25 °C; $t_p$ ≤ 10 μs; pulsed; see <u>Figure 3</u>		-	311	A
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>		-	128	W
T <sub>stg</sub>	storage temperature			-55	175	°C
T <sub>j</sub>	junction temperature			-55	175	°C
Source-drain	diode					
I <sub>S</sub>	source current	$T_{mb} = 25  ^{\circ}C$		-	78	Α
I <sub>SM</sub>	peak source current	$t_p \le 10 \mu\text{s}; \text{ pulsed}; T_{mb} = 25 ^{\circ}\text{C}$		-	311	Α
Avalanche ruggedness						
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$I_D$ = 78 A; $V_{sup}$ ≤ 55 V; $R_{GS}$ = 50 $\Omega$ ; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped		-	94	mJ
E <sub>DS(AL)R</sub>	repetitive drain-source avalanche energy		[3][4][5]	-	-	J

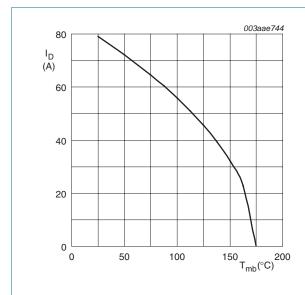
<sup>[1] -16</sup>V accumulated duration not to exceed 168 hrs

<sup>[2]</sup> Accumulated pulse duration not to exceed 5mins.

<sup>[3]</sup> Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.

<sup>[4]</sup> Repetitive avalanche rating limited by an average junction temperature of 170 °C.

<sup>[5]</sup> Refer to application note AN10273 for further information.



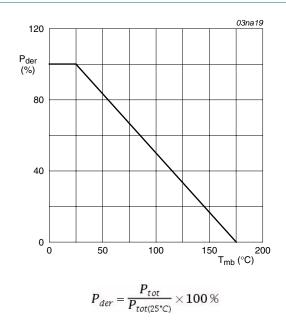


Fig 1. Continuous drain current as a function of mounting base temperature

Fig 2. Normalized total power dissipation as a function of mounting base temperature

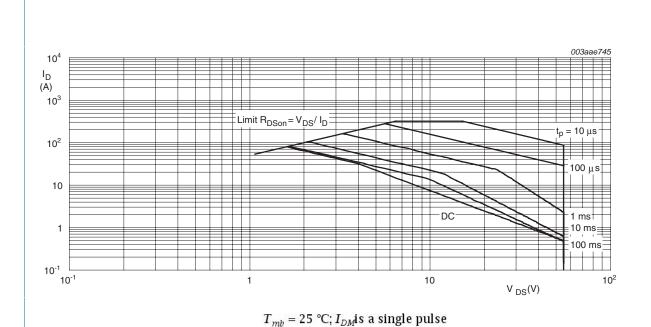
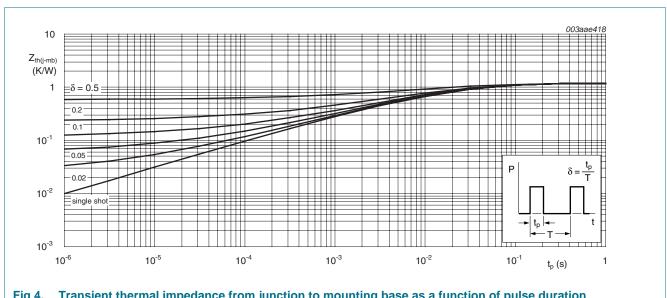


Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

## **Thermal characteristics**

Table 5. **Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	1.17	K/W



Transient thermal impedance from junction to mounting base as a function of pulse duration

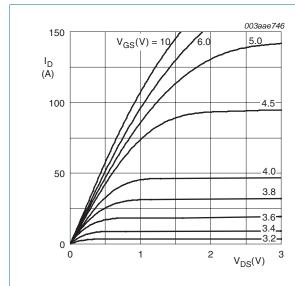
# **Characteristics**

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	aracteristics					
V <sub>(BR)DSS</sub> drain-source breakdown voltage		$I_D = 250 \mu A; V_{GS} = 0 V; T_i = 25 °C$	55	-	-	V
(=::)====	breakdown voltage	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>i</sub> = -55 °C	50	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	$I_D = 1 \text{ mA}$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ °C}$ ; see <u>Figure 9</u> ; see <u>Figure 10</u>	1.8	2.3	2.8	V
		$I_D$ = 1 mA; $V_{DS}$ = $V_{GS}$ ; $T_j$ = -55 °C; see <u>Figure 10</u>	-	-	3.3	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$ ; $T_j = 175$ °C; see <u>Figure 10</u>	0.8	-	-	V
I <sub>DSS</sub>	drain leakage current	$V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ °C}$	-	-	500	μΑ
		$V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	0.02	1	μΑ
I <sub>GSS</sub> gate le	gate leakage current	$V_{DS} = 0 \text{ V}; V_{GS} = 20 \text{ V}; T_j = 25 \text{ °C}$	-	2	100	nΑ
		$V_{DS} = 0 \text{ V; } V_{GS} = -20 \text{ V; } T_j = 25 \text{ °C}$	-	2	100	nΑ
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see Figure 11	-	8.1	9.6	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see Figure 11	-	9.9	13.2	mΩ
		$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see Figure 11	-	10.8	14.5	mΩ
		$V_{GS}$ = 10 V; $I_D$ = 15 A; $T_j$ = 175 °C; see <u>Figure 12</u> ; see <u>Figure 11</u>	-	-	21.2	mΩ
Dynamic	characteristics					
Q <sub>G(tot)</sub>						
Q <sub>G(tot)</sub>	total gate charge	$I_D = 25 \text{ A}$ ; $V_{DS} = 44 \text{ V}$ ; $V_{GS} = 5 \text{ V}$ ; see <u>Figure 13</u> ; see <u>Figure 14</u>	-	34.4	-	nC
Q <sub>G(tot)</sub>			-	34.4 63	-	nC nC
. ,		see <u>Figure 13</u> ; see <u>Figure 14</u> I <sub>D</sub> = 25 A; V <sub>DS</sub> = 44 V; V <sub>GS</sub> = 10 V;	-		-	
$Q_GS$	total gate charge	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V;}$ see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V;}$	-	63	-	nC
Q <sub>GS</sub>	total gate charge gate-source charge	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$	-	63		nC nC
$Q_{GS}$ $Q_{GD}$ $C_{iss}$	total gate charge gate-source charge gate-drain charge	see Figure 13; see Figure 14 $I_D = 25 \text{ A}$ ; $V_{DS} = 44 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; see Figure 13; see Figure 14 $I_D = 25 \text{ A}$ ; $V_{DS} = 44 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; see Figure 13 $I_D = 25 \text{ A}$ ; $V_{DS} = 44 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; see Figure 13; see Figure 14	-	63 10.4 19.5	-	nC nC
$Q_{GS}$ $Q_{GD}$ $C_{iss}$ $C_{oss}$	gate-source charge gate-drain charge input capacitance	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$	-	63 10.4 19.5 2990	- 4000	nC nC nC
Q <sub>GS</sub> Q <sub>GD</sub> C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	gate-source charge  gate-drain charge  input capacitance output capacitance reverse transfer	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$	-	63 10.4 19.5 2990 290	- 4000 350	nC nC nC
$Q_{GS}$ $Q_{GD}$ $C_{iss}$ $C_{oss}$ $C_{rss}$	gate-source charge gate-drain charge input capacitance output capacitance reverse transfer capacitance	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$ $T_j = 25 \text{ °C; see Figure 15}$	-	63 10.4 19.5 2990 290 205	- 4000 350 281	nC nC nC pF pF
$Q_{GS}$ $Q_{GD}$ $C_{iss}$ $C_{oss}$ $C_{rss}$ $t_{d(on)}$	gate-source charge gate-drain charge input capacitance output capacitance reverse transfer capacitance turn-on delay time	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$ $T_j = 25 \text{ °C; see Figure 15}$ $V_{DS} = 45 \text{ V; } R_L = 1.8 \text{ \Omega; } V_{GS} = 10 \text{ V; }$	-	63 10.4 19.5 2990 290 205 16	- 4000 350 281	nC nC pF pF pr
$\begin{array}{c} Q_{GS} \\ \\ Q_{GD} \\ \\ C_{iss} \\ \\ C_{oss} \\ \\ C_{rss} \\ \\ t_{d(on)} \\ \\ t_r \\ \\ t_{d(off)} \\ \end{array}$	gate-source charge gate-drain charge input capacitance output capacitance reverse transfer capacitance turn-on delay time rise time	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$ $T_j = 25 \text{ °C; see Figure 15}$ $V_{DS} = 45 \text{ V; } R_L = 1.8 \text{ \Omega; } V_{GS} = 10 \text{ V; }$	- - - - - -	63 10.4 19.5 2990 290 205 16 45	- 4000 350 281 -	nC nC pF pF pF ns ns
Q <sub>GS</sub>	gate-source charge  gate-drain charge  input capacitance output capacitance reverse transfer capacitance turn-on delay time rise time turn-off delay time	see Figure 13; see Figure 14 $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13}$ $I_D = 25 \text{ A; } V_{DS} = 44 \text{ V; } V_{GS} = 10 \text{ V; }$ $\text{see Figure 13; see Figure 14}$ $V_{GS} = 0 \text{ V; } V_{DS} = 25 \text{ V; } f = 1 \text{ MHz; }$ $T_j = 25 \text{ °C; see Figure 15}$ $V_{DS} = 45 \text{ V; } R_L = 1.8 \text{ \Omega; } V_{GS} = 10 \text{ V; }$	- - - - - -	63 10.4 19.5 2990 290 205 16 45 130	- 4000 350 281 - -	nC nC pF pF pF ns ns

Table 6. Characteristics ... continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Source-drain diode						
V <sub>SD</sub>	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C};$ see <u>Figure 16</u>	-	0.8	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 20 \text{ A}$ ; $dI_S/dt = -100 \text{ A/}\mu\text{s}$ ; $V_{GS} = 0 \text{ V}$ ;	-	48	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = 25 V	-	88	-	nC



 $T_j = 25$  °C;  $t_p = 300 \mu s$ 

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

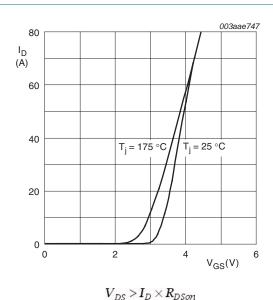
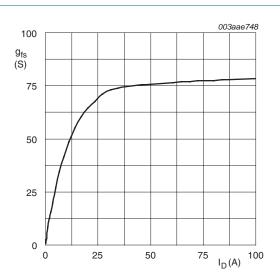
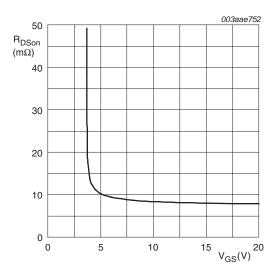


Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$T_j = 25 \,^{\circ}\text{C}; V_{DS} = 15 \,^{\circ}\text{V}$$

Fig 6. Forward transconductance as a function of drain current; typical values



 $T_j = 25$  °C;  $I_D = 15$  A

Fig 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

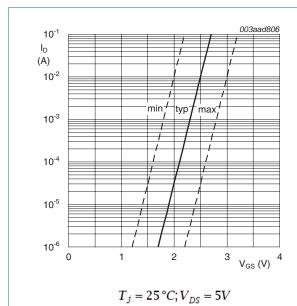


Fig 9. Sub-threshold drain current as a function of gate-source voltage

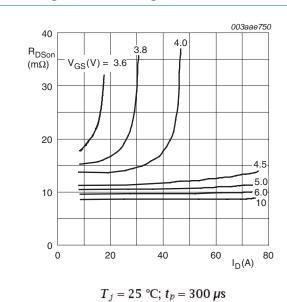
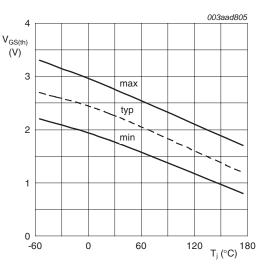


Fig 11. Drain-source on-state resistance as a function of drain current; typical values



 $I_D = 1mA; V_{DS} = V_{GS}$ 

Fig 10. Gate-source threshold voltage as a function of junction temperature

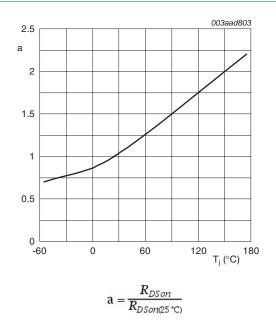
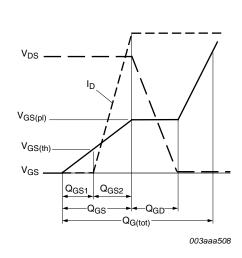
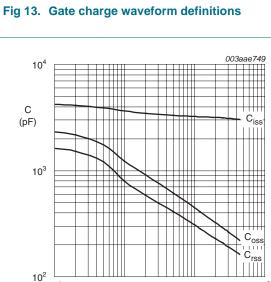


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature





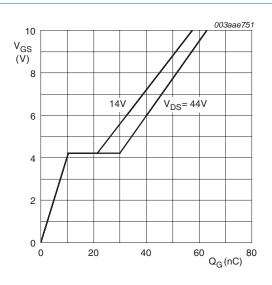
 $V_{GS} = 0 \text{ V; } f = 1 \text{ MHz}$ 

10

10<sup>2</sup>

 $V_{DS}(V)$ 

Fig 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical



 $T_j = 25$  °C;  $I_D = 25$  A

Fig 14. Gate-source voltage as a function of gate charge; typical values

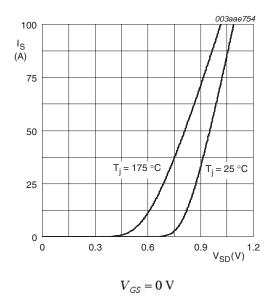


Fig 16. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

10<sup>-1</sup>

# 7. Package outline

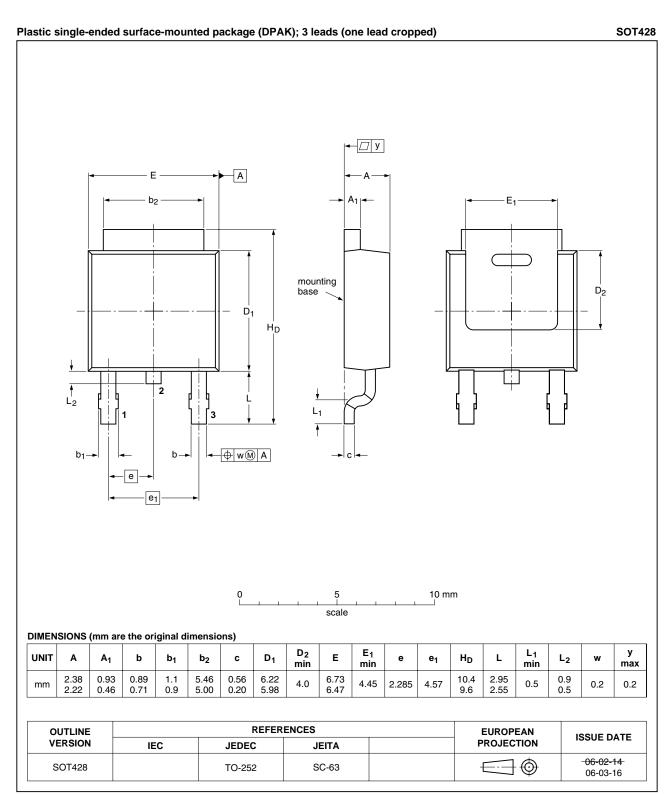


Fig 17. Package outline SOT428 (DPAK)

# 8. Revision history

## Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK6210-55C v.2	20101004	Product data sheet	-	BUK6210-55C v.1
Modifications:	<ul> <li>Status chang</li> </ul>	ed from objective to product.		
BUK6210-55C v.1	20100907	Objective data sheet	-	-

## 9. Legal information

#### 9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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